

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Abraham Ravid	12/07/2006
Boguslaw A. Swedek	12/11/2006
Jeffrey Drue David	12/06/2006
Jun Qian	12/06/2006
Ingemar Carlsson	12/07/2006
Dominic J. Benvegenu	12/07/2006
Harry Q. Lee	12/07/2006
Lakshmanan Karuppiah	12/12/2006

**RECEIVING PARTY DATA**

<b>Name:</b>	Applied Materials, Inc.
<b>Street Address:</b>	3225 Oakmead Village Drive
<b>Internal Address:</b>	M/S 1269
<b>City:</b>	Santa Clara
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95054

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	12822096

**CORRESPONDENCE DATA**

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**CH \$40.00 12822096**

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ATTORNEY DOCKET NUMBER:

10681C01/CMP/05542-651002

NAME OF SUBMITTER:

David Goren

Total Attachments: 3

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**ASSIGNMENT FOR APPLICATION FOR PATENT**

WHEREAS:

Names and Addresses of Inventors:

Abraham Ravid 19756 Wheaton Drive Cupertino, California 95014	Ingemar Carlsson 3474 Spring Creek Lane Milpitas, California 95035
Boguslaw A. Swedek 10135A El Prado Way Cupertino, CA 95014	Dominic J. Benvegna 241 Beverly Drive La Honda, CA 94020
Jeffrey Drue David 2208 Marques Avenue San Jose, CA 95125	Harry Q. Lee 1501 Ben Roe Drive Los Altos, CA 94024
Jun Qian 1000 Kiely Boulevard No. 47 Santa Clara, CA 95051	Lakshmanan Karupiah 2720 Sycamore Grove Place San Jose, CA 95121

*575 Dublin Way Sunnyvale, CA 94087*  
*JSQ.*

(hereinafter referred to as Assignors), have invented a certain invention entitled:

Determining Physical Property of Substrate  
for which application for Letters Patent in the United States was filed on, under Serial No.,  
executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.
2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed;

(b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.


4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

Date: 12/7/2006

  
ABRAHAM RAVID

Date: 12/11/06

  
BOGUSLAW A. SWEDEK

Date: 12/6/06

  
JEFFREY DRUE DAVID

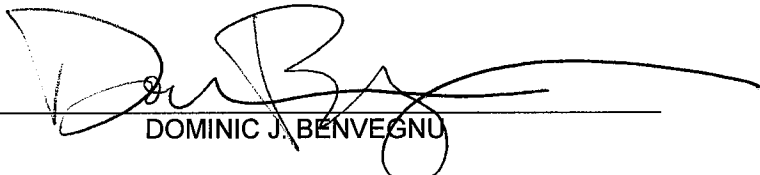
Date: 12/6/06

  
JUN QIAN

Date: 12/7/06

  
INGEMAR CARLSSON

Date: 12/7/06

  
DOMINIC J. BENVEGNO

Date: 12/7/06

  
HARRY Q. LEE

Date: 12/12/2006



LAKSHMANAN KARUPPIAH

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